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(54) Title: HIGH SPEED MANUFACTURE OF MICRO-ELECTRICAL MECHANICAL SYSTEMS ARRAYS

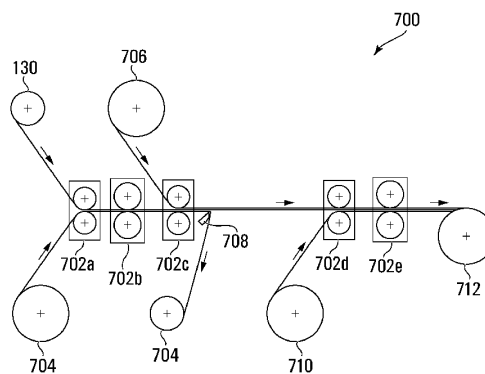


FIG. 7

(57) Abstract: Methods, systems, and techniques for the high speed manufacture of micro-electrical mechanical systems (MEMS) arrays, such as arrays of polymeric capacitive micromachined ultrasonic transducers (CMUTs). A sheet of material from which to form cavities for the devices is obtained, and physical or energy projections are projected into the material to form the cavities. Upper and lower surfaces of the material are respectively contacted with and bonded to upper and lower metalized films. The metalized portions of the upper and lower metalized films may serve as electrodes for a CMUT, and the films themselves may be the CMUT's substrate and membrane.

[Continued on next page]

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